

# YETDA INDUSTRY LTD.

# **Technical Data Sheet**

# MODEL NO: S3535ANB4P-PL

3.5 x 3.5 x 2mm Blue SMD

Features:

●3.5 X 3.5mm

●2000 pcs Per Reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

# Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test	Symbol	Value			l la it
	Condition		Min	Тур	Max	Unit
Dominant wavelength	IF=700mA	λD	460		470	nm
Forward voltage	IF=700mA	VF	3.0	3.4		V
Luminous Flux	IF=700mA		43.5	50		lm
Viewing angle at 50% Iv	IF=10mA	2 <i>θ</i> 1/2	120		140	Deg
Reverse current	Vr=5V	lr			30	μA

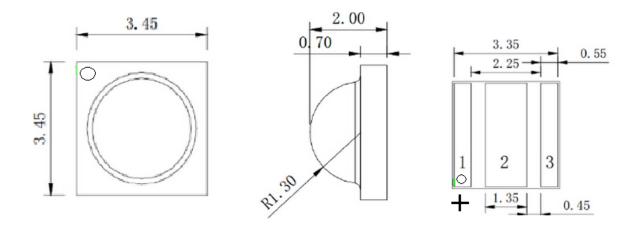
### Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	3	W
Forward current	lf	700	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (Duty 1/10@1KHZ)[1]	Ifp	1000	mA



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# PACKAGING DIMENSIONS (mm):



1. All dimension units are millimeters.

2. All dimension tolerance is ±0.2mm unless otherwise noted.



# **Precautions For Use :**

### **Over - current - proof**

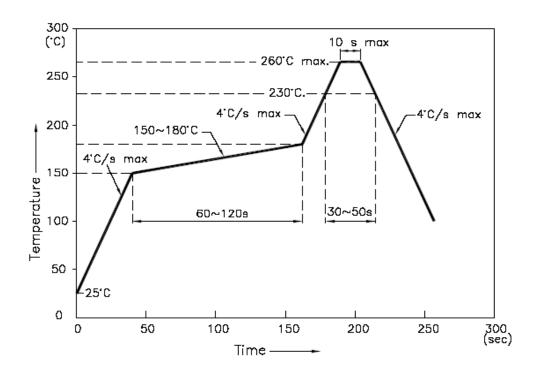
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

#### Storage

1. The operation of temperature and R.H. are  $: 5^{\circ}$ C  $\sim 30^{\circ}$ C,  $60^{\circ}$ R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}C\pm5^{\circ}C$  for 15 hrs.

■ Reflow Temp/Time



### NOTES:

- 1. We recommend the reflow temperature  $245^{\circ}C(\pm 5^{\circ}C)$ .the maximum soldering temperature should be limited to  $260^{\circ}C$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.



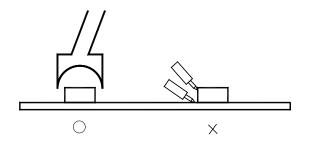
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# ■Soldering iron

Basic spec is  $\leq 5$ sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C.

## Rework

- 1. Customer must finish rework within 5 sec under  $260^{\circ}$ C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.